

TCA9509 电平转换 I²C 和 SMBUS 总线中继器

1 特性

- 双通道双向缓冲器
- 与 I²C 总线和 SMBus 兼容
- B 侧的工作电源电压范围为 2.7V 至 5.5V
- A 侧的工作电源电压范围为 0.9V 至 5.5V
- 0.9V 至 5.5V 和 2.7V 至 5.5V 的电压电平转换
- 高电平有效中继器使能输入
- 低电压端口 A 上无需使用外部上拉电阻器
- 漏极开路 I²C I/O
- 5.5V 耐压 I²C 和使能输入支持混合模式信号操作
- 无闭锁操作
- 适应标准模式和快速模式 I²C 器件和多个控制器
- 支持中继器上的仲裁及时钟延伸
- 断电高阻抗 I²C 总线引脚
- 支持 400kHz 快速 I²C 总线运行速度
- 可采用
 - 1.6mm × 1.6mm、0.4mm 高、0.5mm 间距 QFN 封装
 - 3mm × 3mm 业界通用 MSOP 封装
- 闩锁性能超过 100mA，符合 JESD 78 II 类规范的要求
- ESD 保护性能超过 JESD 22 规范要求
 - 2000V 人体放电模型 (A114-A)
 - 1000V 充电器件模型 (C101)

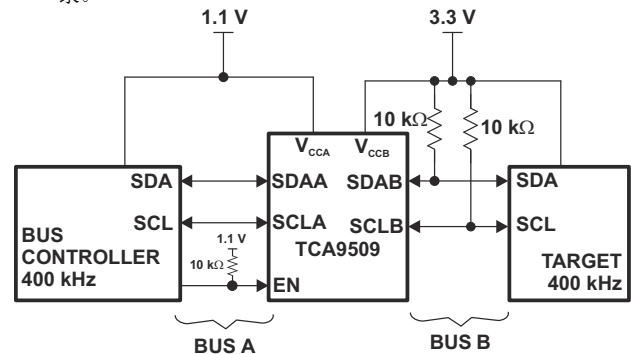
2 应用

- 服务器
- 路由器 (电信交换设备)
- 工业设备
- 产品包含多个 I²C 目标和/或长 PCB 布线

器件信息

器件型号	封装 (1)	本体尺寸 (标称值)
TCA9509	VSSOP (8)	3.00mm × 3.00mm
	X2QFN (8)	1.60mm × 1.60mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



简化版原理图



3 说明

TCA9509 集成电路是一款适用于 I²C/SMBus 系统的 I²C 总线/SMBus 中继器。此器件还可在混合模式应用中提供低电压 (低至 0.9V) 和较高电压 (2.7V 至 5.5V) 间的双向电压电平转换 (上行转换/下行转换)。电平转换期间, 这个器件在不损失系统性能的情况下可扩展 I²C 和相似的总线系统。

TCA9509 可缓冲 I²C 总线上的串行数据 (SDA) 和串行时钟 (SCL) 信号, 因此支持 B 侧 400pF 的总线电容。这款器件也可用于将总线隔离为电压和电容两部分。

TCA9509 具有两类驱动器: A 侧驱动器和 B 侧驱动器。所有输入和 B 侧 I/O 均可承受 5.5V 的过压。器件未通电时 (V_{CCB} 和/或 V_{CCA} = 0V), A 侧 I/O 能够承受 5.5V 的过压。

总线端口 B 驱动器兼容 SMBus I/O 电平, 而 A 侧则使用电流检测机制检测阻止总线锁定的输入或输出低电平信号。A 侧为上拉和 200 Ω 下拉驱动器提供 1mA 电流源。这使 A 侧低电平能适应更小的电压摆幅。A 侧内部缓冲器的输出下拉低电平设定为 0.2V 左右, 而内部缓冲器设定的输入阈值比输出电压低电平大约低 50mV。尽管 A 侧 I/O 为内部低电平驱动, 但该低电平不被识别为输入低电平。这能够避免发生锁定条件。B 侧输出下拉驱动硬低电平, 输入电平设置为 0.3 × SMBus 或 I²C 总线电压电平, 使 B 侧可以连接到任何其他 I²C 总线器件或缓冲器。

TCA9509 驱动器只有在 V_{CCA} 高于 0.8V 并且 V_{CCB} 高于 2.5V 时才能启用。也可使用使能 (EN) 引脚在系统控制下打开和关闭驱动器。请注意, 只能在总线空闲时更改 EN 引脚的状态。

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4 Pin Configuration and Functions

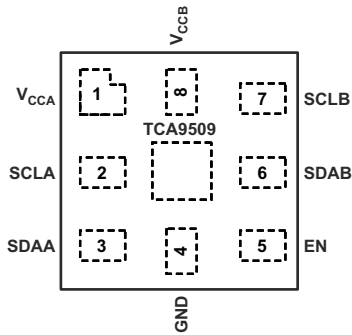


图 4-1. RVH Package, 8-Pin X2QFN, Top View

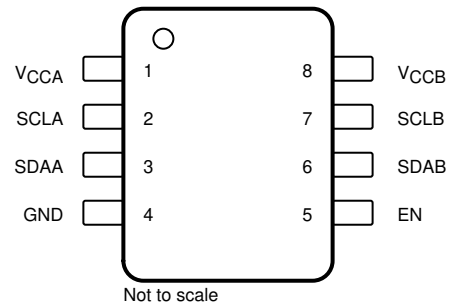


图 4-2. DGK Package, 8-Pin VSSOP, Top View

表 4-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
V _{CCA}	1	Supply	A-side supply voltage (0.9 V to 5.5 V)
SCLA	2	I/O	Serial clock bus, A side.
SDAA	3	I/O	Serial data bus, A side.
GND	4	Supply	Supply ground
EN	5	Input	Active-high repeater enable input
SDAB	6	I/O	Serial data bus, B side. Connect to V _{CCB} through a pull-up resistor.
SCLB	7	I/O	Serial clock bus, B side. Connect to V _{CCB} through a pull-up resistor.
V _{CCB}	8	Supply	B-side and device supply voltage (2.7 V to 5.5 V)
Thermal Attach Pad	-	-	Thermal Attach Pad is not electrically connected and it is recommended to be attached to GND for best thermal performance. This is for the RVH package only.

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CCB}	Supply voltage	- 0.5	6	V
V _{CCA}	Supply voltage	- 0.5	6	V
V _I	Enable input voltage ⁽²⁾	- 0.5	6	V
V _{I/O}	I ² C bus voltage ⁽²⁾	- 0.5	6	V
I _{IK}	Input clamp current	V _I < 0	- 20	mA
I _{OK}	Output clamp current	V _O < 0	- 20	
P _d	Max power dissipation		100	mW
T _J	Junction temperature		125	°C
T _{stg}	Storage temperature	- 65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

		MIN	MAX	UNIT
V _{CCA}	Supply voltage, A-side bus	0.9 ⁽¹⁾	5.5	V
V _{CCB}	Supply voltage, B-side bus	2.7	5.5	V
V _{IH}	High-level input voltage	SDAA, SCLA	0.7 × V _{CCA}	V _{CCA}
		SDAB, SCLB	0.7 × V _{CCB}	5.5
		EN	0.7 × V _{CCA}	5.5
V _{IL}	Low-level input voltage	SDAA, SCLA	- 0.5	0.3
		SDAB, SCLB	- 0.5	0.3 × V _{CCB}
		EN	- 0.5	0.3 × V _{CCA}
I _{OL}	Low-level output current	SDAA, SCLA		10
		SDAB, SCLB		6
T _A	Operating free-air temperature	- 40	85	°C

- (1) Low-level supply voltage

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TCA9509		UNIT
		RVH (X2QFN)	DGK (VSSOP)	
		8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance ⁽²⁾	160.3	222.9	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	66.4	109.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	115.9	144.5	°C/W
ψ_{JT}	Junction-to-top characterization parameter	0.8	34.5	°C/W
ψ_{JB}	Junction-to-board characterization parameter	116.2	142.7	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	80.5	n/a	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.
- (2) The package thermal impedance is calculated in accordance with JESD 51-7.

5.5 Electrical Characteristics

$V_{CCB} = 2.7\text{ V to }5.5\text{ V}$, $V_{CCA} = 0.9\text{ V to } (V_{CCB}-1)$, $T_A = -40^\circ\text{C to }85^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IK}	Input clamp voltage	$I_I = -18\text{ mA}$	-1.5		-0.5	V
V_{OL}	Low-level output voltage	SDAA, SCLA $I_{OL} = 10\ \mu\text{A}$, $V_{ILA} = V_{ILB} = 0\text{ V}$, $V_{CCA} = 0.9\text{ to }1.2\text{ V}$		0.18	0.25	V
		SDAA, SCLA $I_{OL} = 20\ \mu\text{A}$, $V_{ILA} = V_{ILB} = 0\text{ V}$, $1.2\text{ V} < V_{CCA} \leq (V_{CCB} - 1\text{ V})$		0.2	0.3	
$V_{OL} - V_{ILc}$	Low-level input voltage below low-level output voltage	SDAA, SCLA		50		mV
V_{ILc}	SDA and SCL low-level input voltage contention	SDAA, SCLA $V_{CCA} \geq 1.5\text{ V}$ and $V_{CCB} \geq 3.15\text{ V}$	110	150		mV
		SDAA, SCLA $V_{CCA} < 1.5\text{ V}$ or $V_{CCB} < 3.15\text{ V}$	50	100		
V_{OLB}	Low-level output voltage	SDAB, SCLB $I_{OL} = 6\text{ mA}$		0.1	0.2	V
I_{CC}	Quiescent supply current for V_{CCA}	All port A Static high	0.25	0.45	0.9	mA
		All port A Static low	1.25			
I_{CC}	Quiescent supply current for V_{CCB}	All port B Static high	0.2	0.5	1.1	mA
I_I	Input leakage current	SDAB, SCLB $V_I = V_{CCB}$			± 1	μA
			$V_I = 0.2\text{ V}$		10	
		SDAA, SCLA $V_I = V_{CCA}$			± 1	
			$V_I = 0.2\text{ V}$		10	
		EN $V_I = V_{CCB}$			± 1	
			$V_I = 0.2\text{ V}$		-10	
I_{OH}	High-level output leakage current	SDAB, SCLB $V_O = 3.6\text{ V}$			10	μA
		SDAA, SCLA $V_O = 3.6\text{ V}$			10	
C_{IOA}	I/O capacitance of A-side	SCLA, SDAA $V_I = 0\text{ V}$		6.5	7	pF
C_{IOB}	I/O capacitance of B-side	SCLB, SDAB $V_I = 0\text{ V}$	5.5		6.2	pF

5.6 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
t_{su}	Setup time, EN high before Start condition ⁽¹⁾	100		ns
t_h	Hold time, EN high after Stop condition ⁽¹⁾	100		ns

(1) EN should change state only when the global bus and the repeater port are in an idle state.

5.7 I²C Interface Timing Requirements

$T_A = -40^{\circ}\text{C}$ to 85°C (unless otherwise noted)

PARAMETER		V_{CCA} (INPUT)	V_{CCB} (OUTPUT)	TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT	
t_{PHL}	Propagation delay	1.9 V	5 V	EN High		123.1	127.2	132.8	
	port A to port B							ns	
t_{PLH}	Propagation delay	1.9 V	5 V	EN High		88.1	88.8	89.8	
	port B to port A							ns	
t_{PLH}	Propagation delay	1.9 V	5 V	EN High		122.6	125.7	131.7	
	port A to port B							ns	
t_{rise}	Transition time	1.9 V	5 V	EN High		40.1	40.9	41.9	
	port A							ns	
t_{fall}	Transition time	1.9 V	5 V	EN High		57.3	57.5	58.4	
	port B							ns	
t_{fall}	Transition time	1.9 V	5 V	EN High		14.5	16.4	17.9	
	port A							ns	
t_{fall}	Transition time	1.9 V	5 V	EN High		18.7	19.4	20.2	
	port B							ns	
t_{PLH2}	Propagation delay 50% of initial low on Port A to 1.5 V on Port B	1.9 V	5 V			176	177.3	178	ns
f_{MAX}	Maximum switching frequency					400			KHz

(1) Typical values were measured with $V_{CCA} = V_{CCB} = 2.7\text{ V}$ at $T_A = 25^{\circ}\text{C}$, unless otherwise noted.

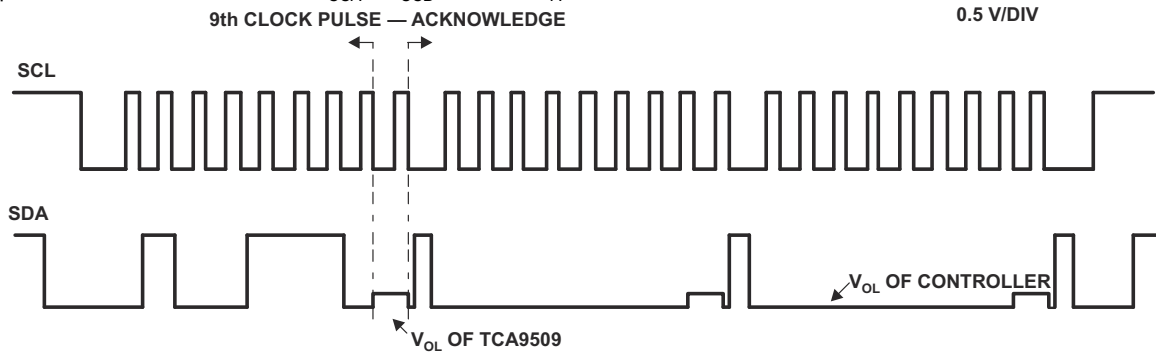


图 5-1. Bus A (0.9-V to 5.5-V Bus) Waveform

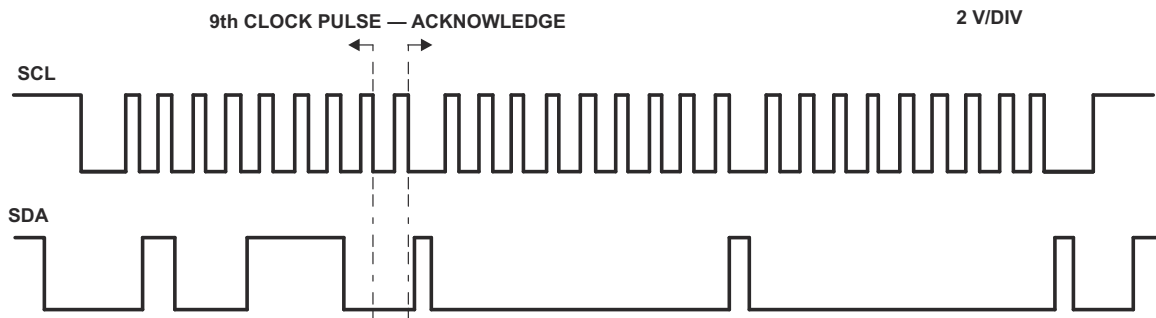
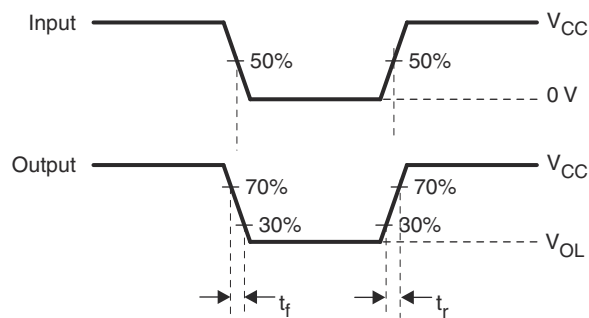
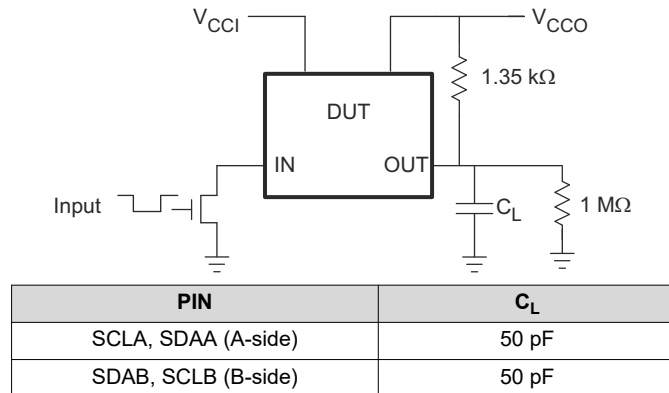


图 5-2. Bus B (2.7-V to 5.5-V Bus) Waveform

6 Parameter Measurement Information



- R_T termination resistance should be equal to Z_{OUT} of pulse generators.
- C_L includes probe and jig capacitance.
- All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, slew rate ≥ 1 V/ns.
- The outputs are measured one at a time, with one transition per measurement.
- t_{PLH} and t_{PHL} are the same as t_{pd} .

图 6-1. Test Circuit and Voltage Waveforms

7 Detailed Description

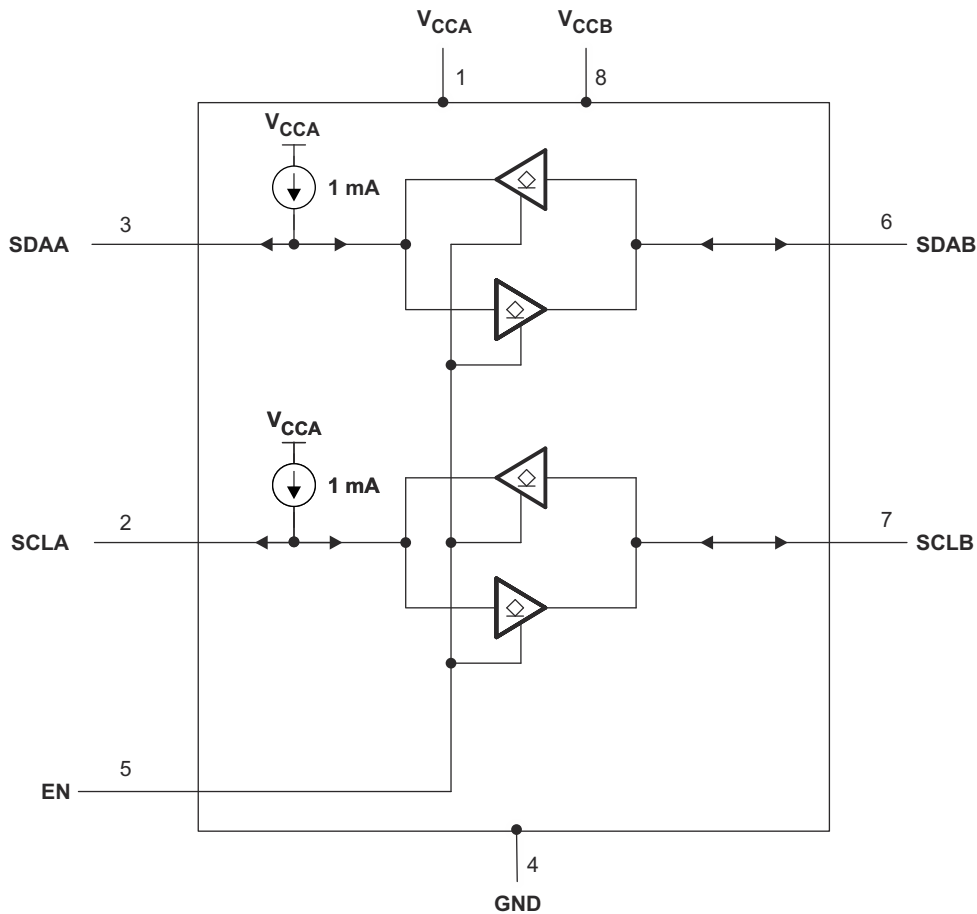
7.1 Overview

This TCA9509 integrated circuit is an I²C bus/SMBus Repeater for use in I²C/SMBus systems. It can also provide bidirectional voltage-level translation (up-translation/down-translation) between low voltages (down to 0.9 V) and higher voltages (2.7 V to 5.5 V) in mixed-mode applications. This device enables I²C and similar bus systems to be extended, without degradation of performance even during level shifting.

The TCA9509 buffers both the serial data (SDA) and the serial clock (SCL) signals on the I²C bus, thus allowing 400-pF bus capacitance on the B-side. This device can also be used to isolate two halves of a bus for voltage and capacitance.

The TCA9509 has two types of drivers - A-side drivers and B-side drivers. All inputs and B-side I/O's are overvoltage tolerant to 5.5V. The A-side I/O's are overvoltage tolerant to 5.5 V when the device is unpowered (V_{CCB} and/or $V_{CCA} = 0V$).

7.2 Functional Block Diagram



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7.3 Feature Description

7.3.1 Two-Channel Bidirectional Buffer

The TCA9509 is a two-channel bidirectional buffer with level-shifting capabilities, featuring an integrated current source on the A-side.

7.3.2 Integrated A-Side Current Source

The A-side ports of the TCA9509 feature an integrated 1 mA current source, eliminating the need for external pull-up resistors on SDAA and SCLA.

7.3.3 Standard Mode and Fast Mode Support

The TCA9509 supports standard mode as well as fast mode I²C. The maximum system operating frequency will depend on system design and delays added by the repeater.

7.4 Device Functional Modes

表 7-1 lists the functional modes for the TCA9509.

表 7-1. Function Table

INPUT EN	FUNCTION
L	Outputs disabled
H	SDAA = SDAB SCLA = SCLB

8 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

8.1 Application Information

The TCA9509 is 5-V tolerant, so it does not require any additional circuitry to translate between 0.9-V to 5.5-V bus voltages and 2.7-V to 5.5-V bus voltages.

When the B-side of the TCA9509 is pulled low by a driver on the I²C bus and the falling edge goes below 0.3 V_{CCB}, it causes the internal driver on the A-side to turn on, causing the A-side to pull down to about 0.2 V (V_{OL}). When the A-side of the TCA9509 falls, a comparator detects the falling edge and causes the internal driver on the B-side to turn on and pull the B-side pin down to ground. In order to illustrate what would be seen in a typical application, refer to 图 5-1. If the bus controller in 图 8-1 were to write to the target through the TCA9509, waveforms shown in 图 5-2 would be observed on the B bus. This looks like a normal I²C bus transmission, except that the high level may be as low as 0.9 V, and the turn on and turn off of the acknowledge signals are slightly delayed.

On the A-side bus of the TCA9509, the clock and data lines would have a positive offset from ground equal to the V_{OL} of the TCA9509. After the eighth clock pulse, the data line is pulled to the V_{OL} of the controller device, which is close to ground in this example. At the end of the acknowledge, the level rises only to the low level set by the driver in the TCA9509 for a short delay, while the B-bus side rises above 0.3 V_{CCB} and then continues high. It is important to note that any arbitration or clock stretching events require that the low level on the A-bus side at the input of the TCA9509 (V_{IL}) be at or below V_{ILC} to be recognized by the TCA9509 and then transmitted to the B-bus side.

8.2 Typical Application

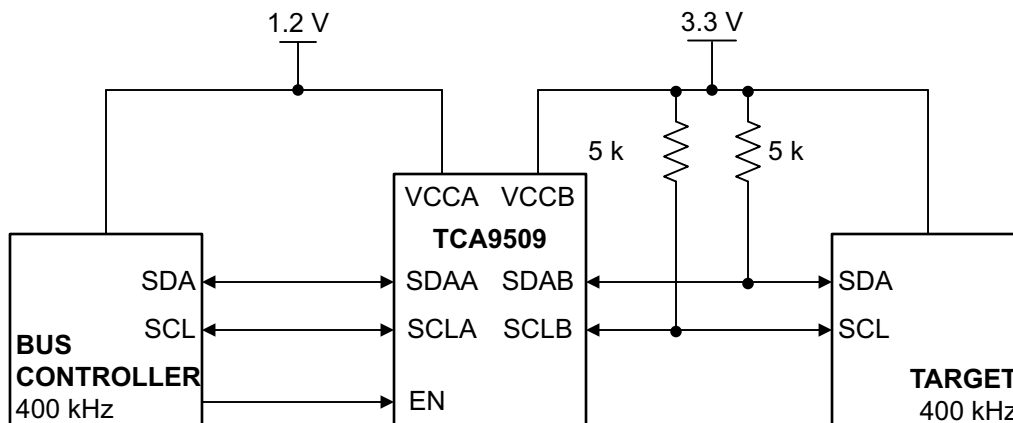


图 8-1. Typical Application, A-side Connected to controller

8.2.1 Design Requirements

A typical application is shown in 图 8-1. In this example, the system controller is running on a 1.2-V I²C bus, and the target is connected to a 3.3-V bus. Both buses run at 400 kHz. Controller devices can be placed on either bus. For the level translating application, the following should be true: V_{CCA} ≤ (V_{CCB} - 1 V)

- V_{CCA} = 0.9 V to 5.5 V
- V_{CCB} = 2.7 to 5.5 V
- A-side ports must not be connected together

- Pullup resistors should not be placed on the A-side ports

8.2.2 Detailed Design Procedure

8.2.2.1 Clock Stretching Support

The TCA9509 can support clock stretching, but care needs to be taken to minimize the overshoot voltage presented during the hand-off between the target and controller. This is best done by increasing the pull-up resistor value on B-side ports.

8.2.2.2 V_{ILC} and Pulldown Strength Requirements

For the TCA9509 to function correctly, all devices on the A-side must be able to pull the A-side below the voltage input low contention level (V_{ILC}). This means that the V_{OL} of any device on the A-side must be below V_{ILC} min.

The V_{OL} can be adjusted by changing the I_{OL} through the device which is set by the pull-up resistance value. The pull-up resistance on the A-side must be carefully selected to ensure that the logic levels will be transferred correctly to the B-side.

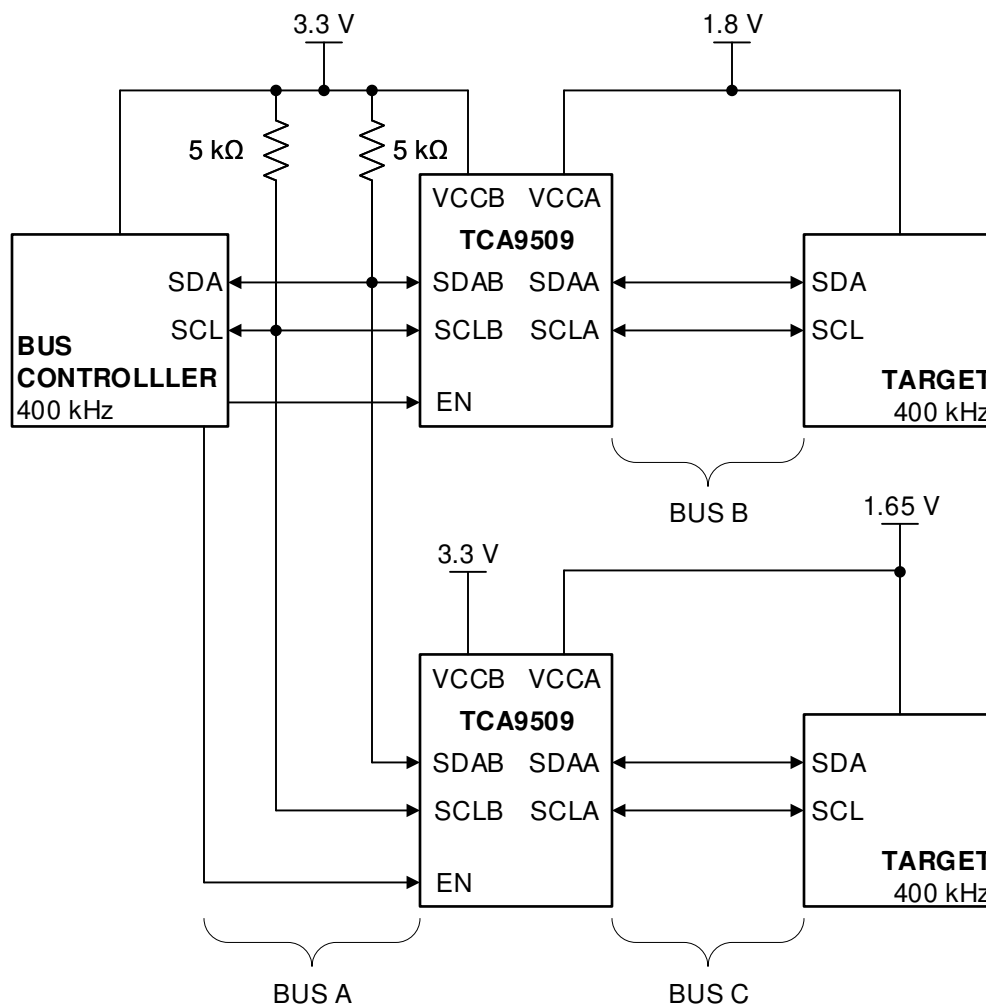


图 8-2. Typical Star Application

Multiple B-sides of TCA9509 can be connected in a star configuration, allowing all nodes to communicate with each other. The A-sides should not be connected together when used in a star/parallel configuration.

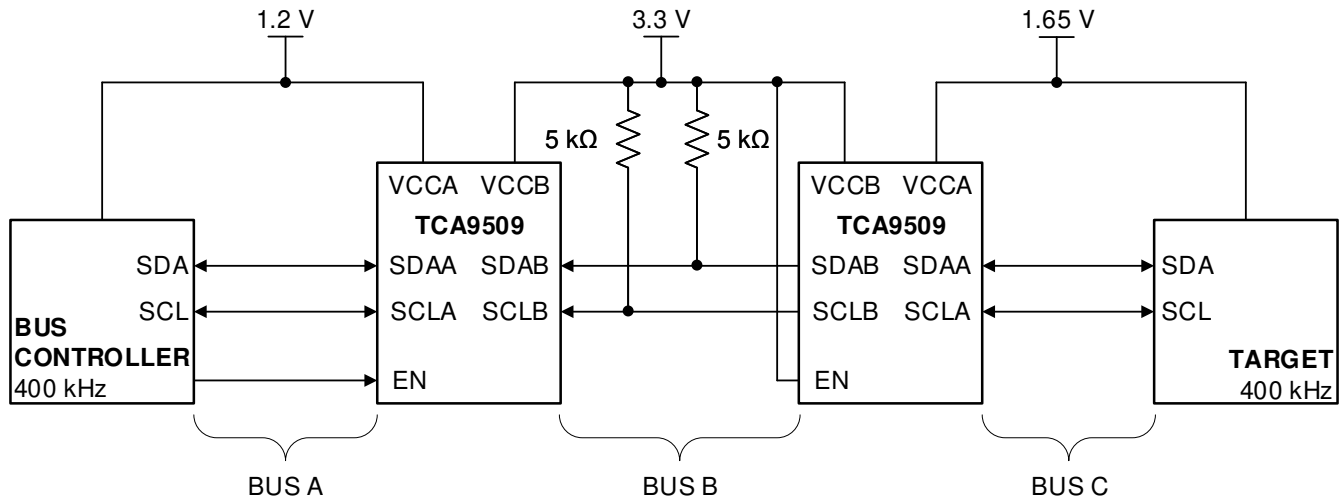


图 8-3. Typical Series Application, Two B-Sides Connected Together

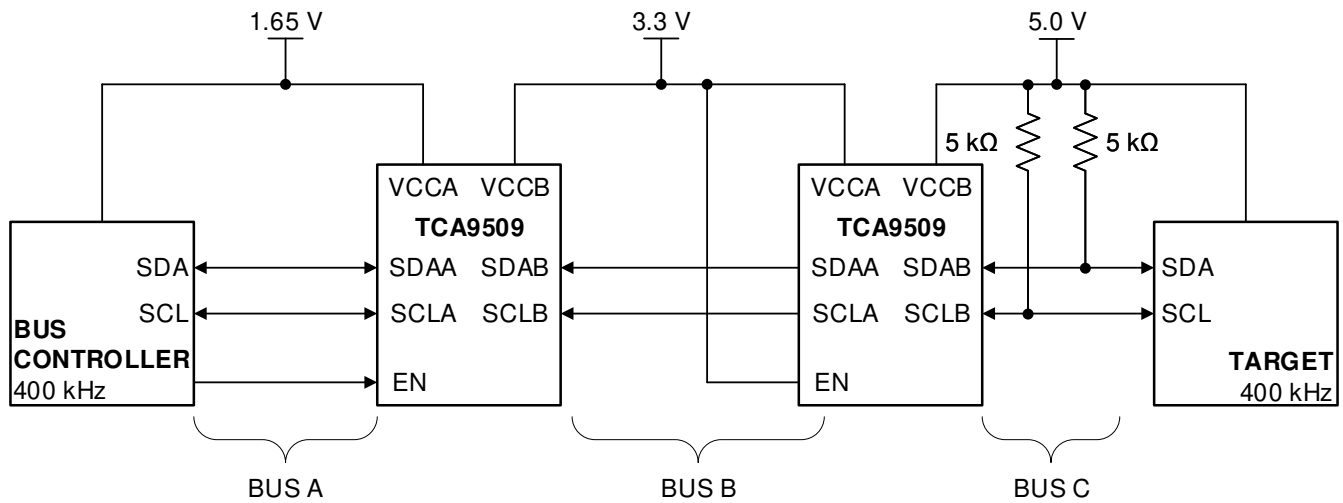


图 8-4. Typical Series Application, A-side Connected to B-Side

To further extend the I²C bus for long traces/cables, multiple TCA9509 devices can be connected in series as long as the A-side is connected to the B-side and $V_{CCA} \leq (V_{CCB} - 1\text{ V})$ must also be met. Series connections can also be made by connecting both B-sides together while following power supply rule $V_{CCA} \leq (V_{CCB} - 1\text{ V})$. I²C bus target devices can be connected to any of the bus segments. The number of devices that can be connected in series is limited by repeater delay/time-of-flight considerations on the maximum bus speed requirements.

9 Power Supply Recommendations

V_{CCB} and V_{CCA} can be applied in any sequence at power up. The TCA9509 includes a power-up circuit that keeps the output drivers turned off until V_{CCB} is above 2.5 V and the V_{CCA} is above 0.8 V. After power up and with the EN high, a low level on the B-side (below $0.3 \times V_{CCB}$) turns the corresponding A-side driver (either SDA or SCL) on and drives the A-side down to approximately 0.2 V. When the B-side rises above $0.3 \times V_{CCB}$, the A-side pull-down driver is turned off and the external pull-up resistor pulls the pin high. When the A-side falls first and goes below $0.3 \times V_{CCA}$, the B-side driver is turned on and the B-side pulls down to 0 V. The A-side pull-down is not enabled unless the A-side voltage goes below 0.4 V. If the A-side low voltage does not go below 0.5 V, the B-side driver turns off when the A-side voltage is above $0.7 \times V_{CCA}$. If the A-side low voltage goes below 0.4 V, the A-side pull-down driver is enabled, and the A-side is able to rise to only 0.5 V until the B-side rises above $0.3 \times V_{CCB}$.

A 100 nF a decoupling capacitor should be placed as close to the V_{CCA} and V_{CCB} pins in order to provide proper filtering of supply noise.

10 Layout

10.1 Layout Guidelines

There are no special layout procedures required for the TCA9509.

It is recommended that the decoupling capacitors be placed as close to the VCC pins as possible.

10.2 Layout Example

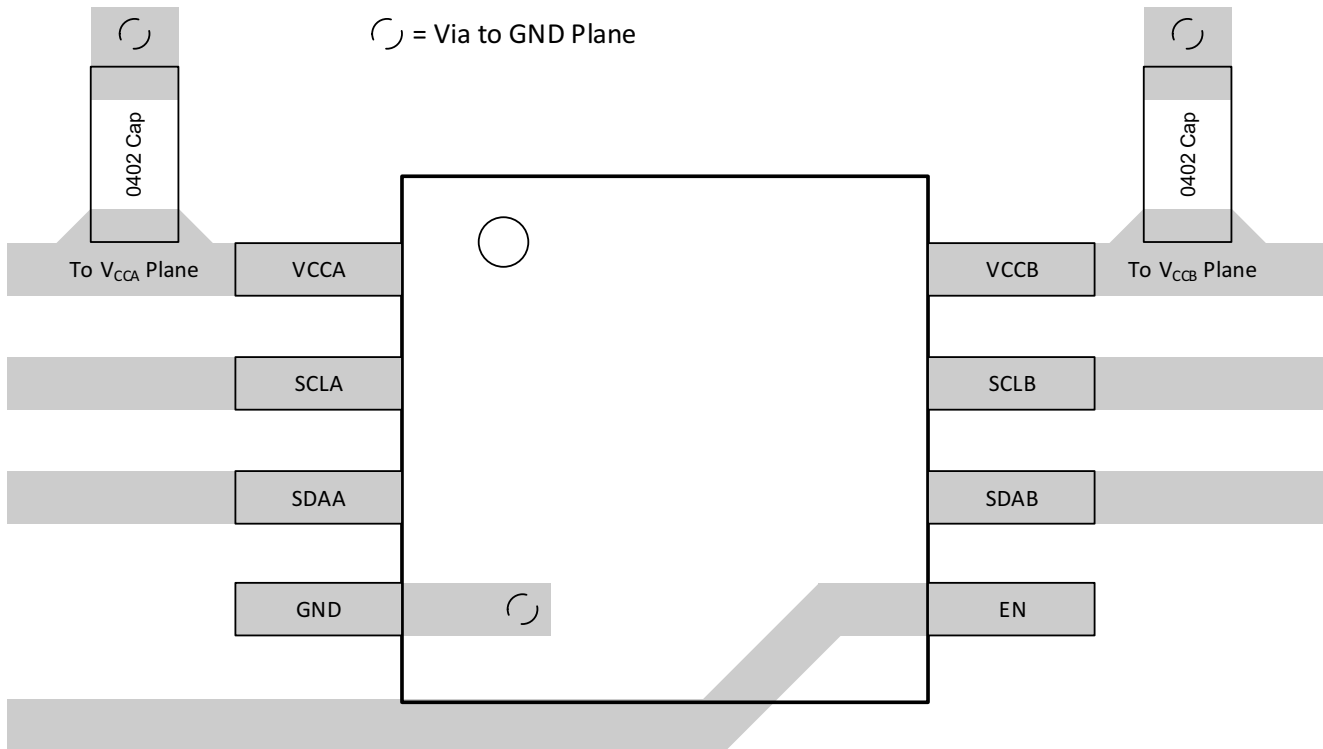


图 10-1. Example Layout

11 Device and Documentation Support

11.1 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

11.2 支持资源

[TI E2E™ 中文支持论坛](#) 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [使用条款](#)。

11.3 商标

TI E2E™ is a trademark of Texas Instruments.

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11.4 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

11.5 术语表

[TI 术语表](#)

本术语表列出并解释了术语、首字母缩略词和定义。

12 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision D (April 2021) to Revision E (October 2024) Page

- Updated Tape and Reel Information..... 18

Changes from Revision C (December 2017) to Revision D (April 2021) Page

- 将数据表中的术语 *主站和从站* 更改为 *控制器和目标* 1
- Changed I_{CC} Quiescent supply current for V_{CCB} MIN value from 0.5 mA to 0.20 mA and the TYP value from 0.9 mA to 0.5 mA in the *Electrical Characteristics* table.....6
- Changed text From: "Multiple B-sides of TCA9509 s..." To: "Multiple B-sides of TCA9509..."..... 12
- Updated Tape and Reel Information..... 18

Changes from Revision B (January 2012) to Revision C (December 2017) Page

- 添加了 *ESD* 等级表、特性说明部分、器件功能模式、应用和实施部分、电源相关建议部分、布局部分、器件和文档支持部分以及机械、封装和可订购信息部分..... 1
- Added junction temperature to the *Absolute Maximum Ratings*5
- Changed thermal information for RVH and DGK packages 6
- Changed V_{I_LC}, added Test Conditions with new MIN and TYP values in the *Electrical Characteristics* table....6
- Updated Bus A (0.9-V to 5.5-V Bus) Waveform..... 7
- Updated Bus B (2.7-V to 5.5-V Bus) Waveform..... 7

Changes from Revision A (October 2011) to Revision B (January 2012) Page

- 向数据表添加了 DGK 封装和封装信息..... 1

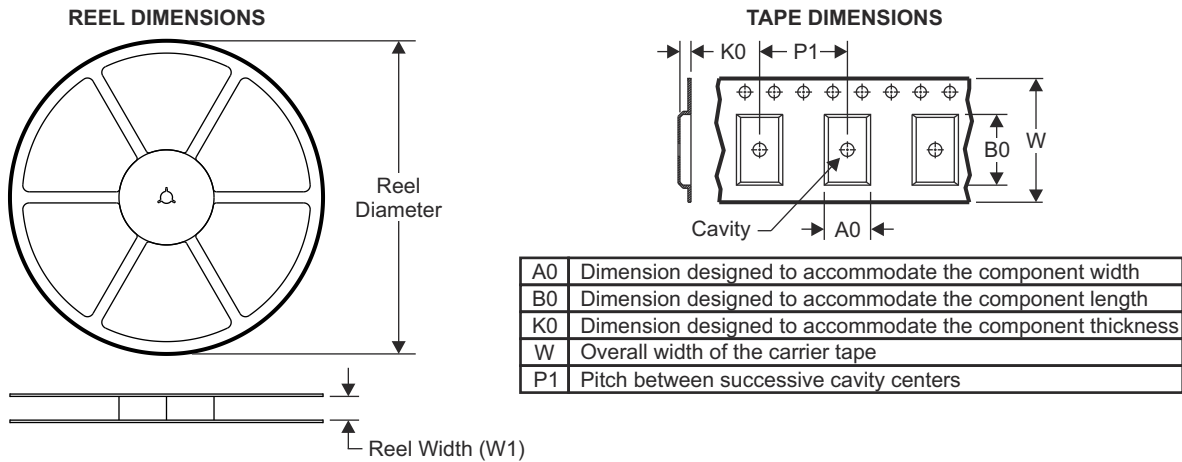
Changes from Revision * (August 2011) to Revision A (October 2011) Page

- 将文档中多个实例的 V_{CCA} 工作电压下限更正为 0.9V..... 1
- 更改了“特性”B 侧的“工作电源电压范围”值错误将“B 侧 0.9V 至 5.5V”更改为“B 侧 2.7V 至 5.5V”... 1
- 更改了“特性”A 侧的“工作电压范围”值错误将“A 侧 2.7V 至 V_{CCB} - 1V”更改为“A 侧 0.9V 至 V_{CCB} - 1V” 1

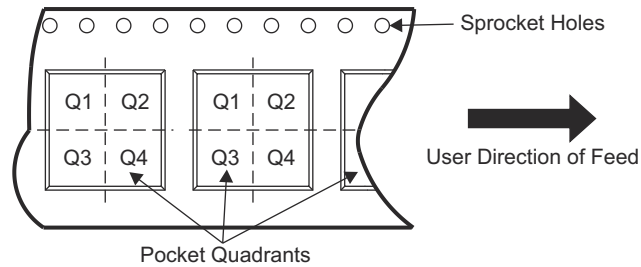
13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

13.1 Tape and Reel Information

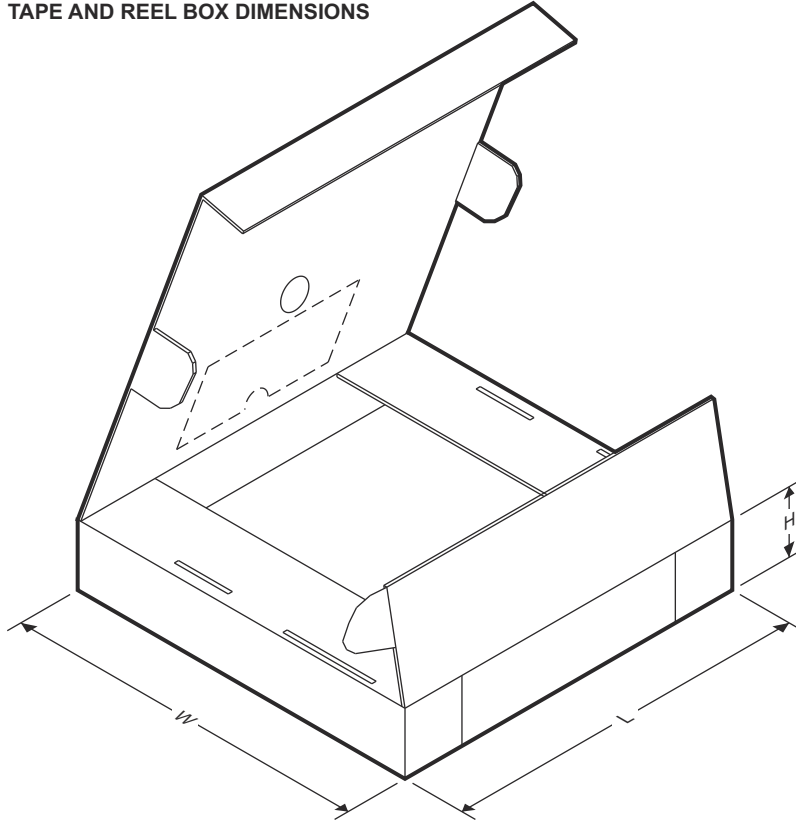


QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9509MRVHR	X2QFN	RVH	8	5000	180.0	8.4	1.8	1.8	0.5	4.0	8.0	Q1
TCA9509RVHR	X2QFN	RVH	8	5000	180.0	8.4	1.8	1.8	0.5	4.0	8.0	Q3
TCA9509DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9509MRVHR	X2QFN	RVH	8	5000	183.0	183.0	20.0
TCA9509RVHR	X2QFN	RVH	8	5000	202.0	201.0	28.0
TCA9509DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TCA9509DGKR	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU SN NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(7KO, 7KQ)
TCA9509DGKR.A	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(7KO, 7KQ)
TCA9509DGKR.B	Active	Production	VSSOP (DGK) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(7KO, 7KQ)
TCA9509MRVHR	Active	Production	X2QFN (RVH) 8	5000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	7K
TCA9509MRVHR.A	Active	Production	X2QFN (RVH) 8	5000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	7K
TCA9509MRVHR.B	Active	Production	X2QFN (RVH) 8	5000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	7K
TCA9509RVHR	Active	Production	X2QFN (RVH) 8	5000 LARGE T&R	Yes	NIPDAU NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	7K
TCA9509RVHR.A	Active	Production	X2QFN (RVH) 8	5000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	7K
TCA9509RVHR.B	Active	Production	X2QFN (RVH) 8	5000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	7K

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

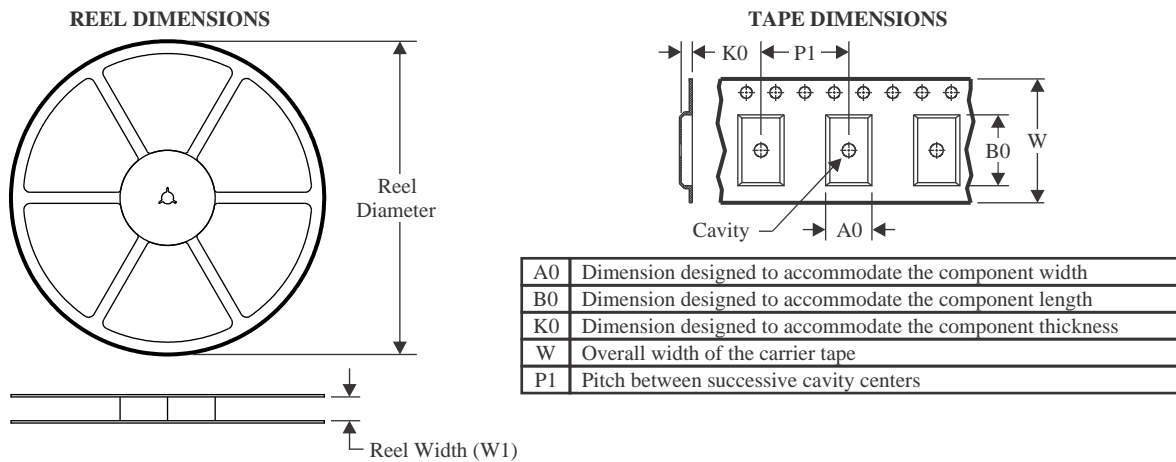
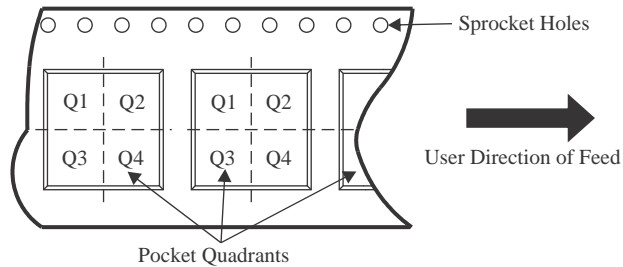
(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative

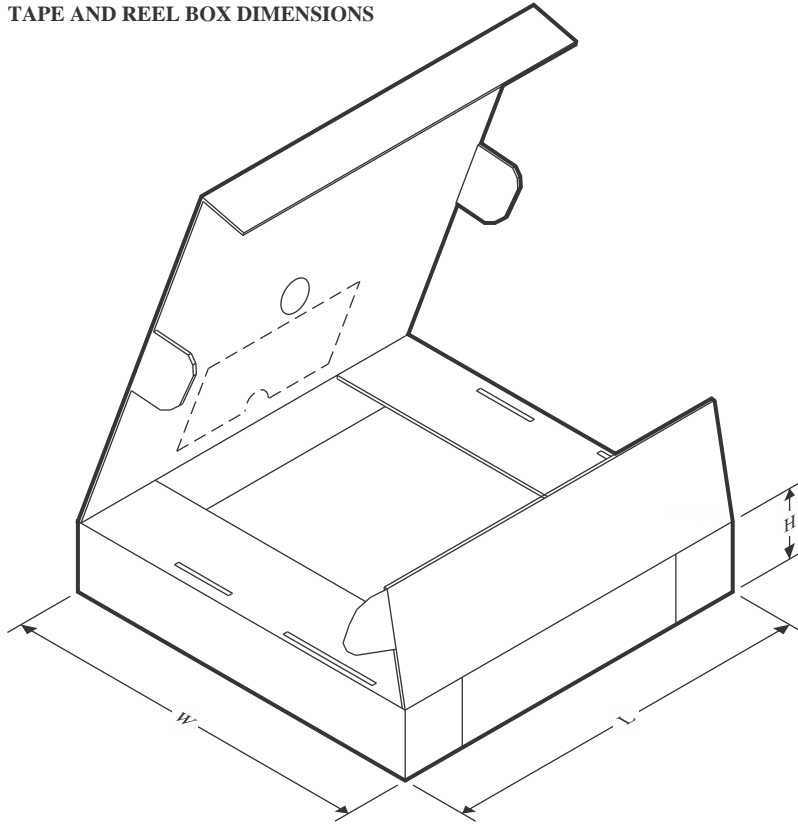
and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


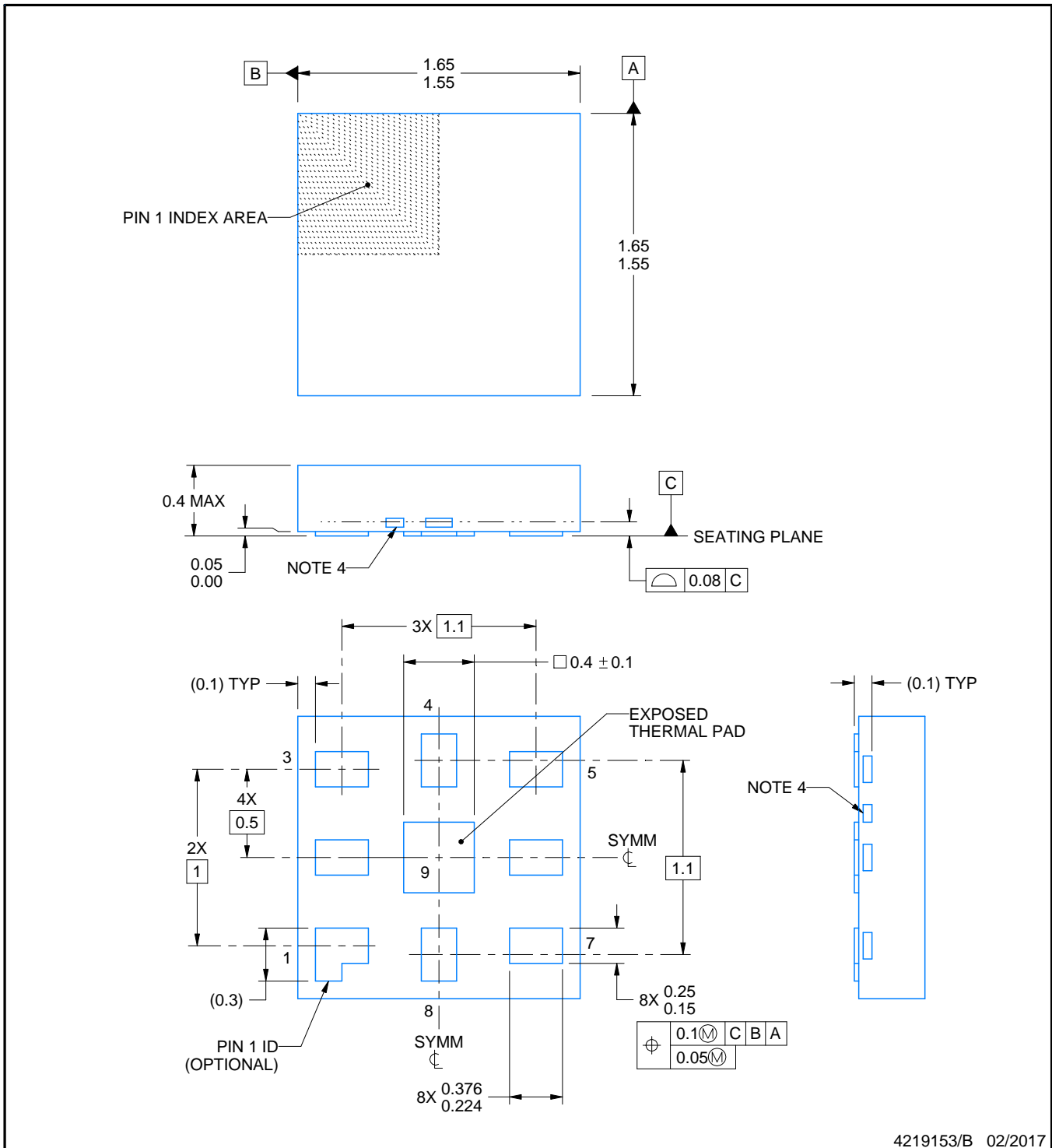
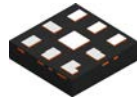
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TCA9509DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TCA9509DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TCA9509MRVHR	X2QFN	RVH	8	5000	180.0	8.4	1.8	1.8	0.5	4.0	8.0	Q1
TCA9509RVHR	X2QFN	RVH	8	5000	180.0	9.5	1.73	1.73	0.72	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TCA9509DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
TCA9509DGKR	VSSOP	DGK	8	2500	353.0	353.0	32.0
TCA9509MRVHR	X2QFN	RVH	8	5000	183.0	183.0	20.0
TCA9509RVHR	X2QFN	RVH	8	5000	184.0	184.0	19.0



4219153/B 02/2017

NOTES:

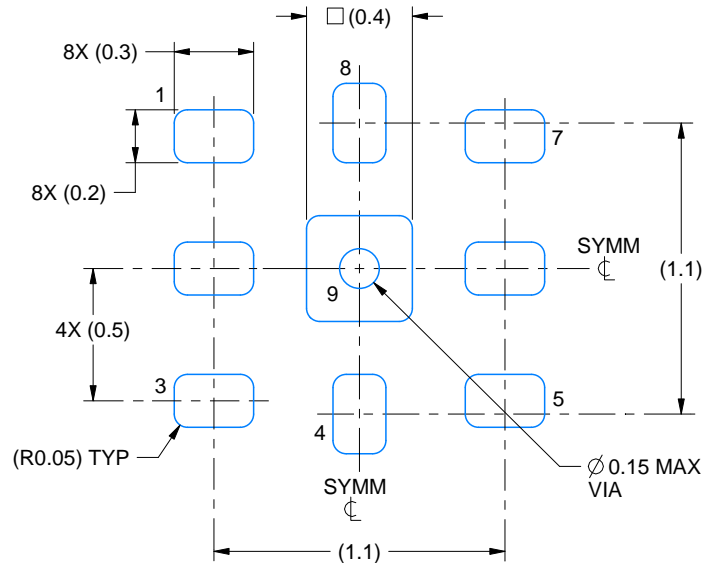
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.
4. Exposed tie bars may vary in size and location.

EXAMPLE BOARD LAYOUT

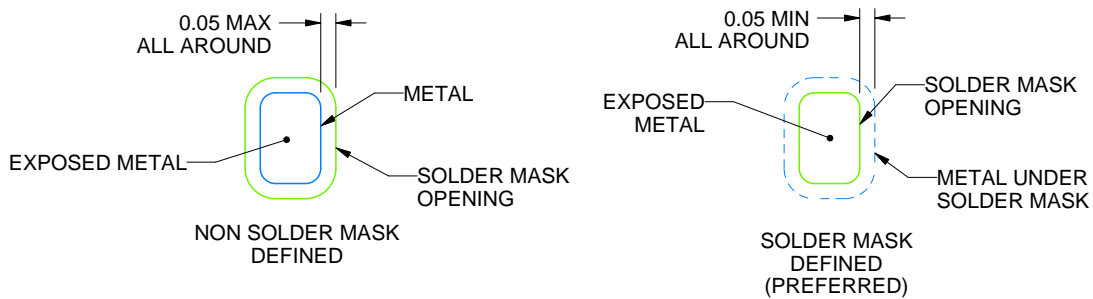
RVH0008A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:35X



SOLDER MASK DETAILS

4219153/B 02/2017

NOTES: (continued)

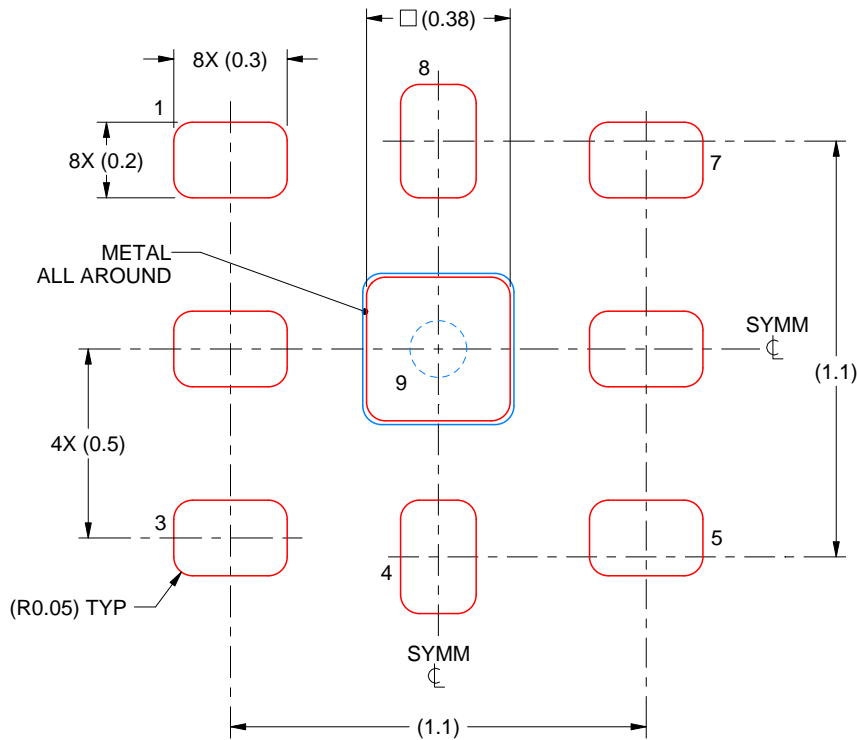
5. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
6. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

RVH0008A

X2QFN - 0.4 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE BASED ON 0.1 mm THICK STENCIL

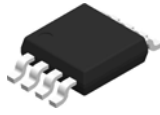
EXPOSED PAD 9
90% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:50X

4219153/B 02/2017

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

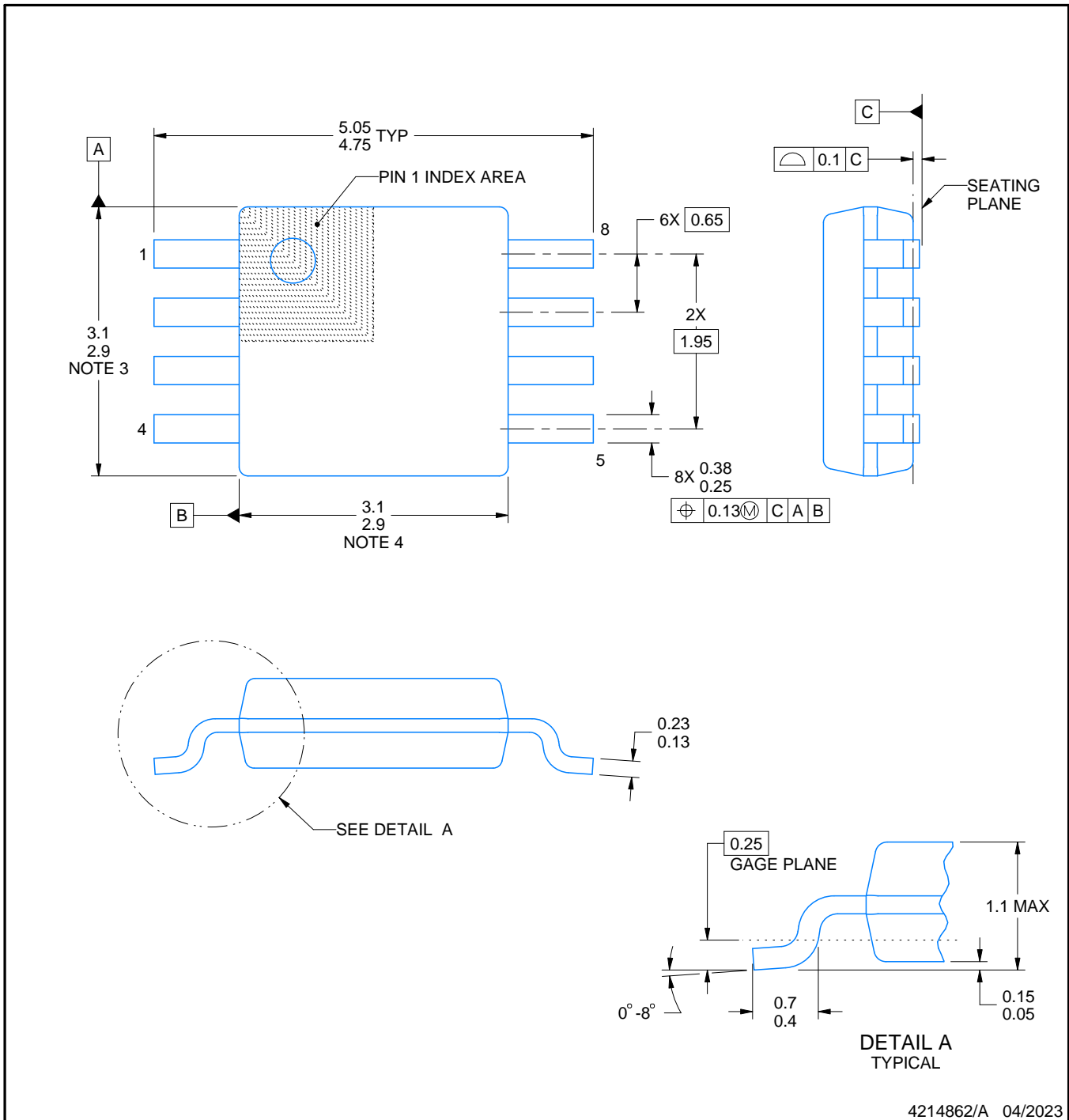
DGK0008A



PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4214862/A 04/2023

NOTES:

PowerPAD is a trademark of Texas Instruments.

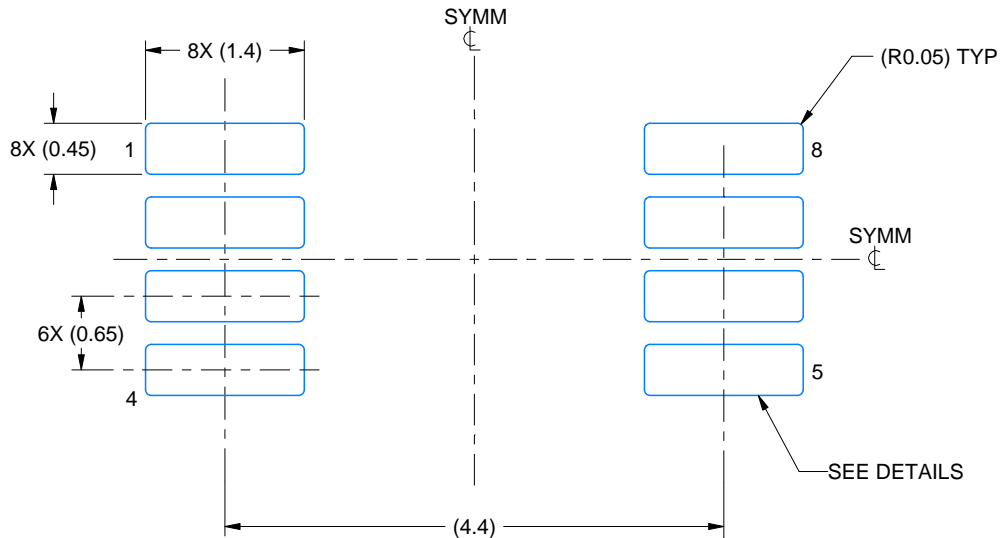
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

EXAMPLE BOARD LAYOUT

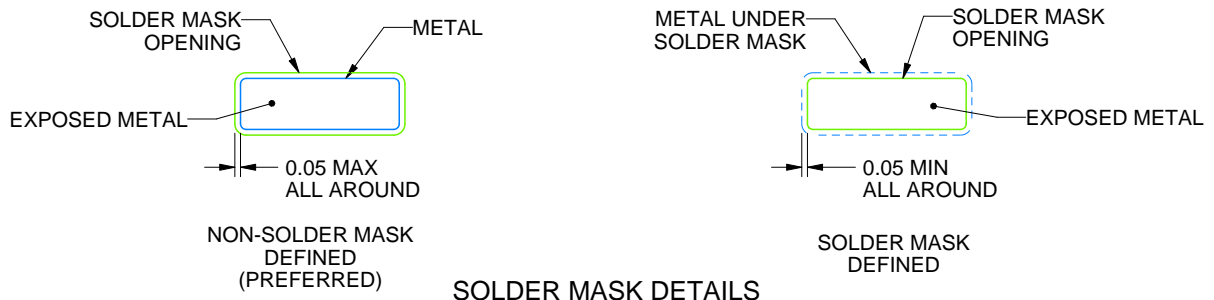
DGK0008A

™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 15X



SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

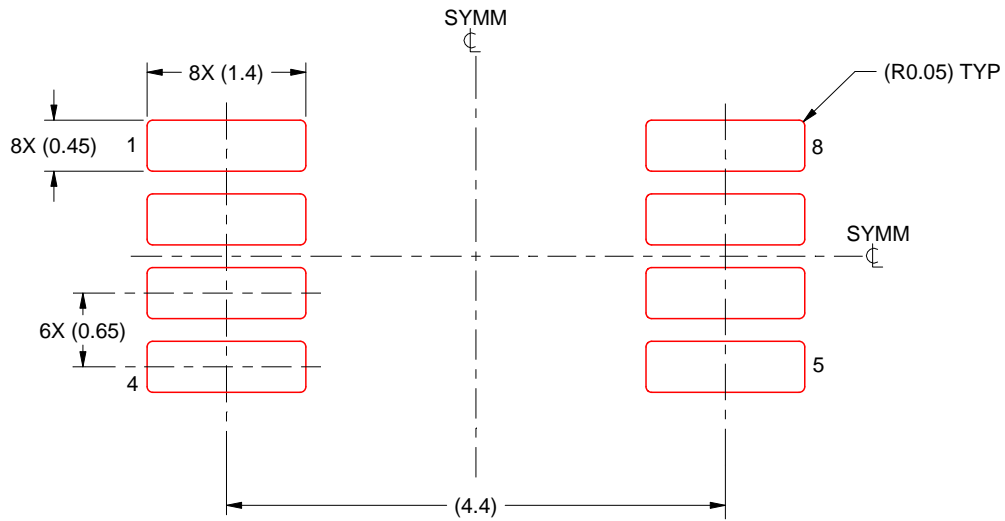
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

DGK0008A

TM VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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最后更新日期：2025 年 10 月